



Product Change Notification: CAAN-23VSTB654

Date:

15-Jul-2026

Product Category:

Memory

Notification Subject:

CCB 8103 Final Notice: Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package.

Affected CPNs:

[CAAN-23VSTB654_Affected_CPN_07152026.pdf](#)

[CAAN-23VSTB654_Affected_CPN_07152026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	UTAC Thai Limited	UTAC Thai Limited	Microchip Technology Thailand	Yes

Qual Report Availability												X		
Final PCN Issue Date								X						
Estimated Implementation Date								X						

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Note 1: This final PCN will be updated to include the Qualification report as soon as it is completed.

Note 2: Please be advised the qualification completion times may be extended because of unforeseen business conditions.

Revision History:

February 27, 2026: Issued initial notification.

July 15, 2026: Issued final notification. Provided estimated first ship date to be on July 17, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CAAN-23VSTB654_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

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CAAN-23VSTB654 - CCB 8103 Final Notice: Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package.

Affected Catalog Part Numbers (CPN):

SST25PF040CT-40V/NP

USBF4100T-V/NP

SST25PF040CT-40I/NP

USBF4100T-I/NP

SST25PF040CT-40E/NP-125

SST25PF040CT-40E/NP

SST25WF020AT-40I/NP



MICROCHIP QUALIFICATION PLAN SUMMARY

PCN#: CAAN-23VSTB654

**Date:
February 06, 2026**

**Qualification of MMT as an additional assembly site for
SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125,
SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-
40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part
numbers (CPN) available in 8L UDFN (2x3x0.55mm) package. This
is Q100 Grade 1 qualification.**

Purpose: Qualification of MMT as an additional assembly site for SST25PF040CT-40E/NP, SST25PF040CT-40E/NP-125, SST25PF040CT-40I/NP, SST25PF040CT-40V/NP, SST25WF020AT-40I/NP, USBF4100T-I/NP and USBF4100T-V/NP catalog part numbers (CPN) available in 8L UDFN (2x3x0.55mm) package. This is Q100 Grade 1 qualification.

CCB No.: 8103

<u>Misc.</u>	Assembly site	MMT
	BD Number	BD-004200-01
	MP Code (MPC)	T0C01QPRXVA2
	Part Number (CPN)	USBF4100T-V/NPVAO
	MSL information	MSL1
	Assembly Shipping Media (T/R, Tube/Tray)	T/R
	Base Quantity Multiple (BQM)	3000
	Reliability Site	MTAI
<u>Lead-Frame</u>	Paddle size	Chip on Lead design
	Material	EFTEC-64T
	DAP Surface Prep	Ag on lead only
	Treatment	Roughened
	Process	Etched
	Lead-lock	No
	Part Number	10100875
	Lead Plating	Matte tin
<u>Bond Wire</u>	Material	Au
<u>Die Attach</u>	Part Number	ATB F125E1
	Conductive	No
<u>MC</u>	Part Number	G700LTD
<u>PKG</u>	Package Type	UDFN
	Pin/Ball Count	8
	PKG width/size	2x3

Test Name	Conditions	Reliability Stress Read Point Grade 1: -40°C to +125°C (MCHP E Temp)	Pre & Post Reliability Stress Test Temperature Grade 1: -40°C to +125°C (MCHP E Temp)	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hours of steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.			22	5	1	27	>95% lead coverage	5	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011			5	0	1	5	0 fails after TC	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001			5	0	1	5	0	5	30 bonds from a min. 5 devices.
External Visual	Mil. Std. 883-2009/2010			All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	JESD22-A103 +175°C	Grade 1: 500 hrs (+175°C)	Grade 1: +25°C, +85°C, +125°C	45	5	1	50	0	21 - 83	Spares should be properly identified.
Preconditioning - Required for surface mount devices	J-STD-020 JESD22-A113 +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type. MSL-1 @260C°		Grade 1: +25°C, +85°C, +125°C	231	15	3	738	0	15	Spares should be properly identified.
HAST	JESD22-A101 or A110 +130°C/85% RH for 96 hrs	Grade 1: 96 hrs (+130°C/85% RH)	Grade 1: +25°C, +85°C, +125°C	77	5	3	246	0	10 - 14	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A102, A118, or A101 +130°C/85% RH for 96 hrs	Grade 1: 96 hrs (+130°C/85% RH)	Grade 1: +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104 and Appendix 3 -55°C to +150°C	Grade 1: 1000 cycles (-55°C to +150°C)	Grade 1: +25°C, +85°C, +125°C	77	5	3	246	0	15 - 60	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.